ELECTRICAL CHARACTERISTICS (T_A = 0°C to 70°C unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Typ.*	Max	Unit
Forward Voltage	V_F	I_F = 16mA		1.45	1.8	V
Reverse Voltage	V_R	I_R = 10µA, T_A = 25°C	5.0			V
Temperature Coefficient of V_F	$\Delta V_F/\Delta T_A$	I_F = 16mA		-1.6		mV/°C

OUTPUT

Parameter	Symbol	Test Condition	Min	Typ.*	Max	Unit
High Level Supply Current	I_{CCH}	I_F = 0mA, V_O = Open, V_{CC} = 15V, T_A = 25°C		0.05	1	µA
		I_F = 0mA, V_O = Open, V_{CC} = 15V			2	
Low Level Supply Current	I_{CCL}	I_F = 16mA, V_O = Open, V_{CC} = 15V		100	200	µA

COUPLED

Parameter	Symbol	Test Condition	Min	Typ.*	Max	Unit
Current Transfer Ratio	CTR	I_F = 16mA, V_O = 0.4V, V_{CC} = 4.5V, T_A = 25°C	20		50	%
		I_F = 16mA, V_O = 0.5V, V_{CC} = 4.5V	15			
High Level Output Current	I_{OH}	I_F = 0mA, V_O = V_{CC} = 5.5V, T_A = 25°C		0.001	0.5	µA
		I_F = 0mA, V_O = V_{CC} = 15V, T_A = 25°C		0.001	1	
		I_F = 0mA, V_O = V_{CC} = 15V			50	
Low Level Output Voltage	V_{OL}	I_F = 16mA, I_O = 3mA, V_{CC} = 4.5V, T_A = 25°C			0.4	V
		I_F = 16mA, I_O = 2.4mA, V_{CC} = 4.5V			0.5	

* Typical values at T_A = 25°C

ELECTRICAL CHARACTERISTICS (T_A = 0°C to 70°C unless otherwise specified)

Switching Characteristics (V_{CC} = 5V unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ.*	Max	Unit
Propagation Delay Time to Logic Low	T_{PHL}	I_F = 16mA, R_L = 1.9kΩ, T_A = 25°C		0.4	0.8	µs
		I_F = 16mA, R_L = 1.9kΩ,			1.0	
Propagation Delay Time to Logic High	T_{PLH}	I_F = 16mA, R_L = 1.9kΩ, T_A = 25°C		0.35	0.8	µs
		I_F = 16mA, R_L = 1.9kΩ,			1.0	ns
Common Mode Transient Immunity at Logic High	CM_H	ICPLM452 I_F = 0mA, R_L = 1.9kΩ, V_{CM} = 10Vp-p, T_A = 25°C	5000			V/µs
		ICPLM453 I_F = 0mA, R_L = 1.9kΩ, V_{CM} = 1500Vp-p, T_A = 25°C	15000			
Common Mode Transient Immunity at Logic Low	CM_L	ICPLM452 I_F = 16mA, R_L = 1.9kΩ, V_{CM} = 10Vp-p, T_A = 25°C	5000			V/µs
		ICPLM453 I_F = 16mA, R_L = 1.9kΩ, V_{CM} = 1500Vp-p, T_A = 25°C	15000			

* Typical values at T_A = 25°C

CM_H – The maximum tolerable rate of rise of the common mode voltage dV_{CM}/t, to ensure the output will remain in the HIGH state (i.e., V_{OUT} > 2.0V).

CM_L – The maximum tolerable rate of fall of the common mode voltage to dV_{CM}/t, to ensure the output will remain in the LOW output state (i.e., V_{OUT} < 0.8V).

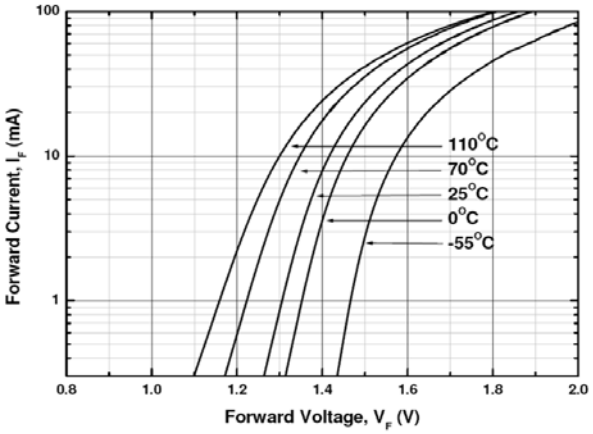


Fig 1 Forward Current vs Forward Voltage

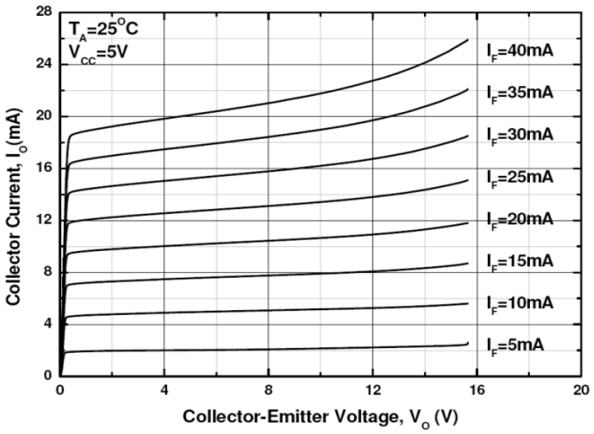


Fig 2 Output Current vs Output Voltage

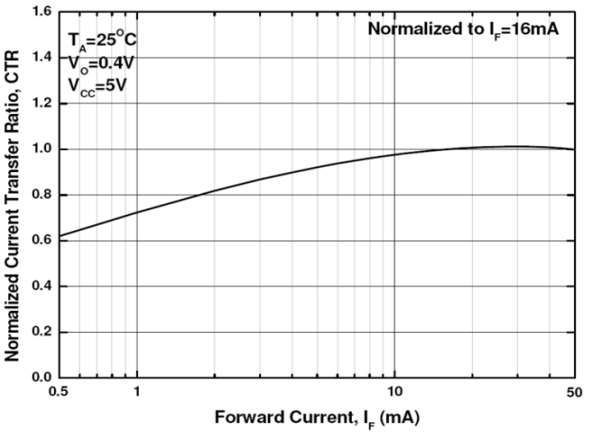


Fig 3 Normalized CTR vs Forward Current

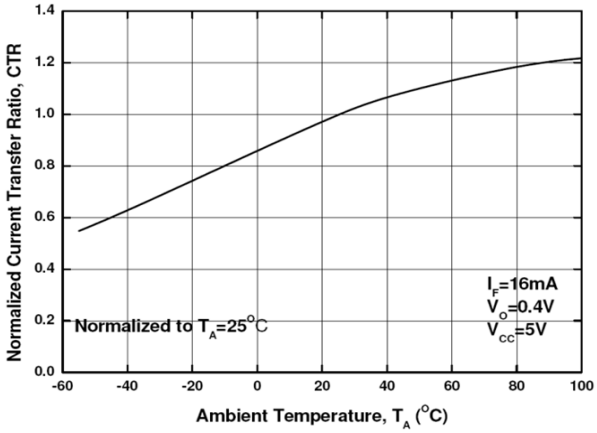


Fig 4 Normalized CTR vs T_A

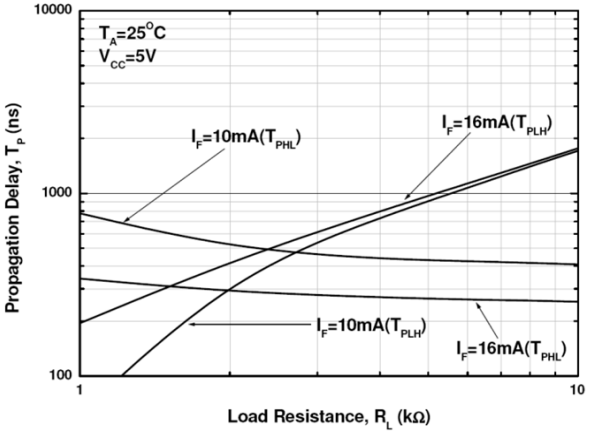


Fig 5 Propagation Delay vs Load Resistance

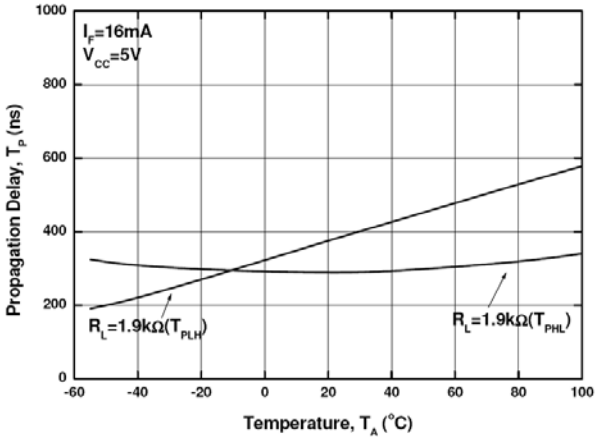


Fig 6 Propagation Delay vs T_A

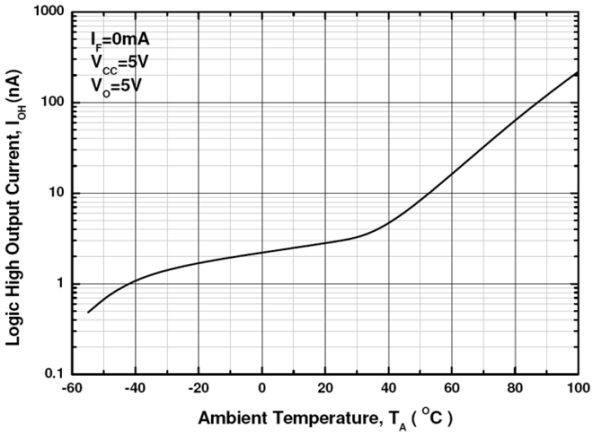


Fig 7 Logic High Output Current vs T_A

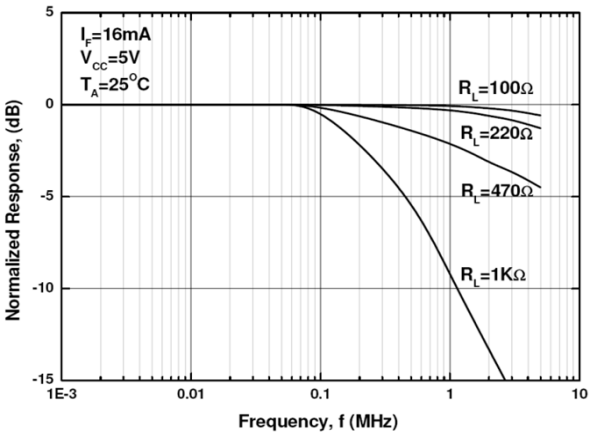


Fig 8 Frequency Response

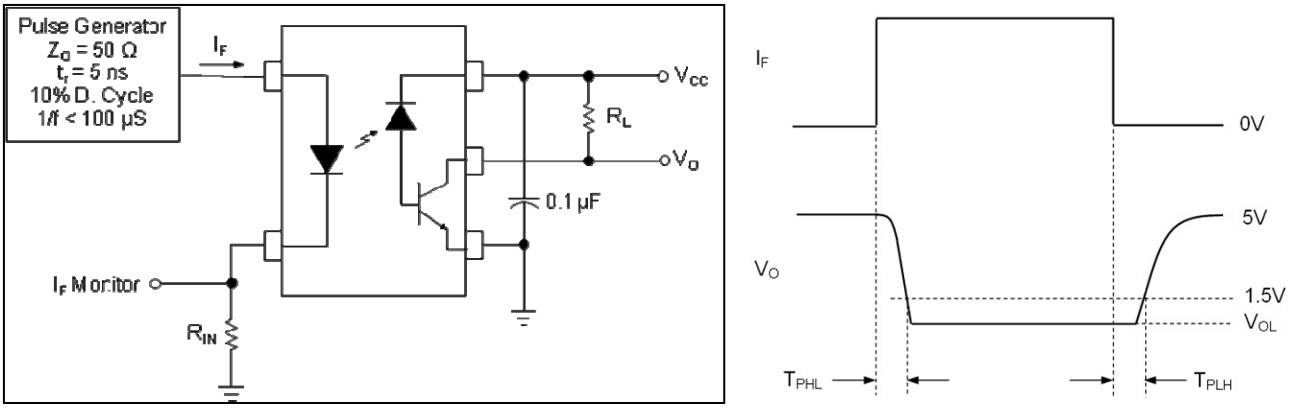


Fig 9 Switching Time Test Circuit

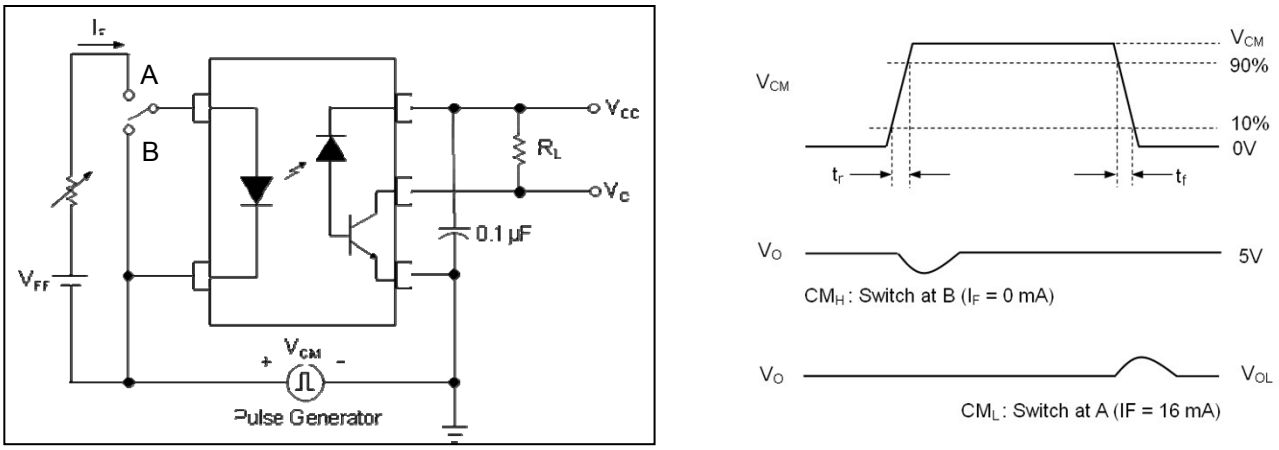


Fig 10 Common Mode Transient Immunity Test Circuit

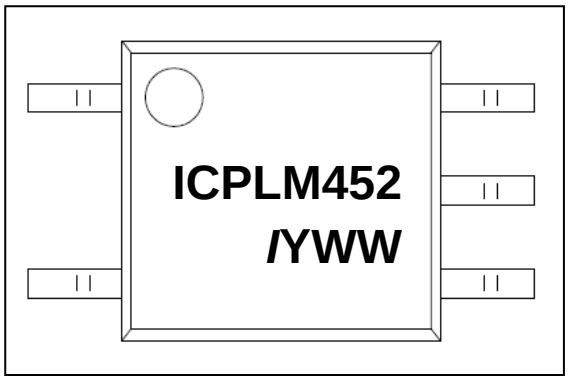
Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{CM}/dt on the leading edge of the common mode pulse signal V_{CM}, to assure that the output will remain in a logic high state (i.e., $V_O > 2.0V$).

Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{CM}/dt on the trailing edge of the common mode pulse signal, V_{CM}, to assure that the output will remain in a logic low state (i.e., $V_O < 0.8V$).

ORDER INFORMATION

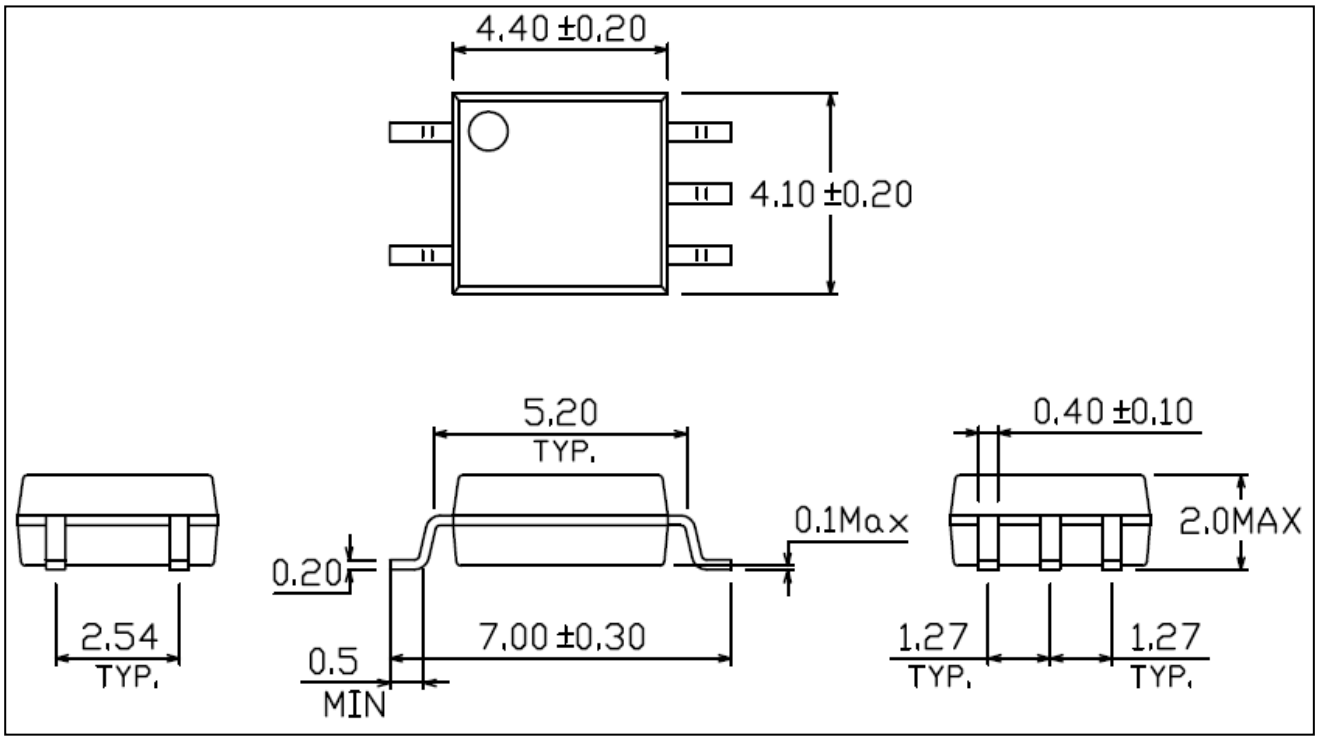
ICPLM452, ICPLM453			
After PN	**PN**	**Description**	**Packing quantity**
None	ICPLM452, ICPLM453	Surface Mount Tape & Reel	3000 pcs per reel

DEVICE MARKING

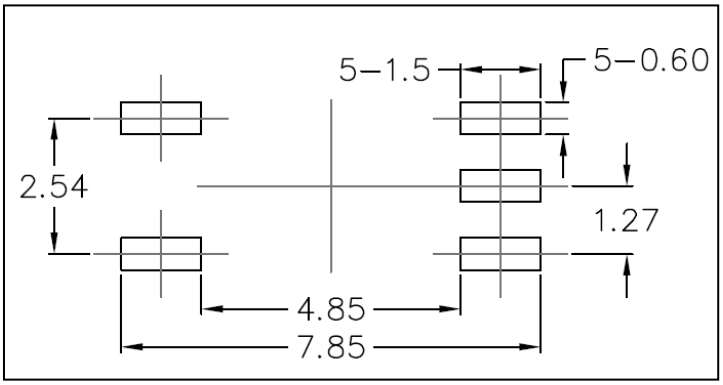


ICPLM600	denotes Device Part Number (ICPLM452 is used as example)
Y	denotes 1 digit Year code
WW	denotes 2 digit Week code
I	denotes Isocom

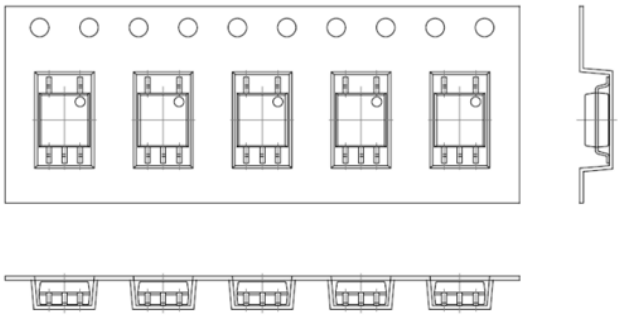
PACKAGE DIMENSIONS (mm)



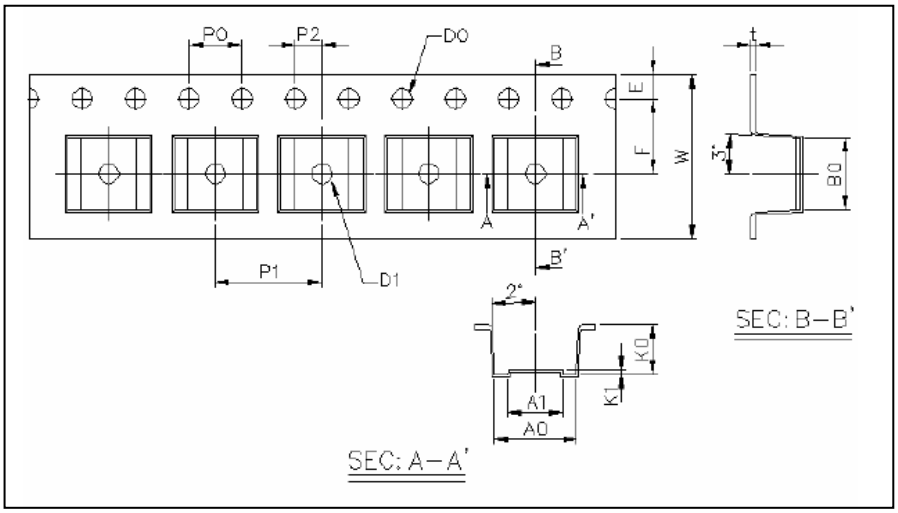
RECOMMENDED PAD LAYOUT (mm)



TAPE AND REEL PACKAGING

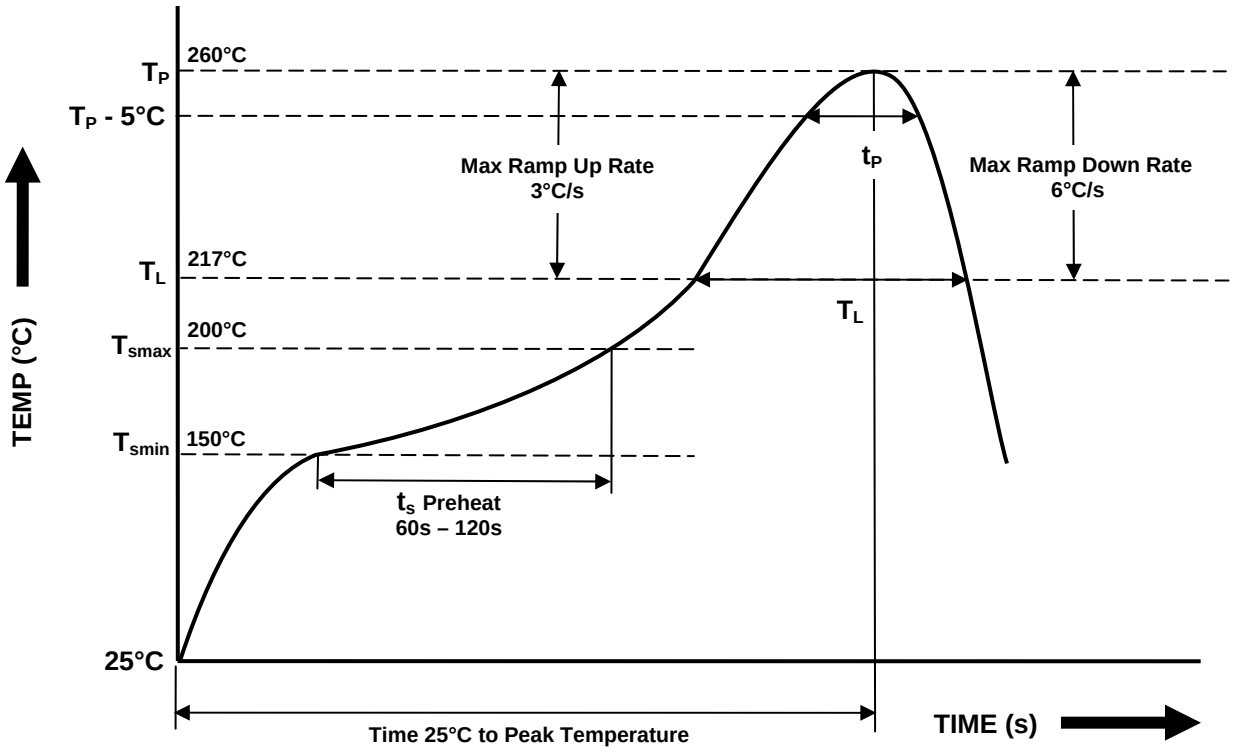


Direction of feed from reel



Dimension No.	**A0**	**A1**	**B0**	**D0**	**D1**	**E**	**F**
Dimension (mm)	6.2±0.1	4.1±0.1	5.28±0.1	1.5±0.1	1.5±0.3	1.75±0.1	5.5±0.1
Dimension No.	**P0**	**P1**	**P2**	**t**	**W**	**K0**	**K0**
Dimension (mm)	4.0±0.1	8.0±0.1	2.0±0.1	0.4±0.1	12.0 +0.3/-0.1	3.7±0.1	0.3±0.1

IR REFLOW SOLDERING TEMPERATURE PROFILE
(One Time Reflow Soldering is Recommended)



Profile Details	Conditions
Preheat - Min Temperature (T_{SMIN}) - Max Temperature (T_{SMAX}) - Time T_{SMIN} to T_{SMAX} (t_s)	 150°C 200°C 60s - 120s
Soldering Zone - Peak Temperature (T_P) - Liquidous Temperature (T_L) - Time within 5°C of Actual Peak Temperature (T_P – 5°C) - Time maintained above T_L (t_L) - Ramp Up Rate (T_L to T_P) - Ramp Down Rate (T_P to T_L)	 260°C 217°C 30s 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T_{smax} to T_P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max

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- The contents described herein are subject to change without prior notice.

- Do not immerse device body in solder paste.

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COMPONENTS

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